INTEGRATED CIRCUITS

DATA SHEET



74F273AOctal D flip-flop

Product specification

1996 Mar 12

IC15 Data Handbook





Octal D flip-flop

74F273A

FEATURES

- High impedance inputs for reduced loading (20µA in Low and High states)
- Ideal buffer for MOS microprocessor or memory
- Eight edge-triggered D-type flip-flops
- Buffered common clock
- Buffered asynchronous Master Reset
- See 74F377A for clock enable version
- See 74F373 for transparent latch version
- See 74F374 for 3-State version

DESCRIPTION

The 74F273 has eight edge—triggered D–type flip—flops with individual D inputs and Q outputs. The common buffered Clock (CP) and Master Reset ($\overline{\text{MR}}$) inputs load and reset (clear) all flip—flops simultaneously.

The register is fully edge—triggered. The state of each D input, one setup time before the Low–to–High clock transition, is transferred to the corresponding flip–flop's Q output.

All outputs will be forced Low independently of Clock or Data inputs by a Low voltage level on the $\overline{\text{MR}}$ input. The device is useful for applications where the true output only is required and the CP and $\overline{\text{MR}}$ are common to all elements.

TYPE	TYPICAL f _{MAX}	TYPICAL SUPPLY CURRENT (TOTAL)
74F273A	170MHz	25mA

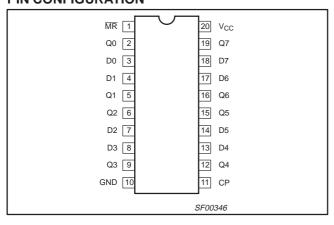
ORDERING INFORMATION

PACKAGE	ES	COMMERCIAL I V _{CC} = 5V±10 T _{amb} = 0°C to	0%;	PKG. DWG. #
20-pin plastic	DIP	74F273AN	١	SOT146-1
20-pin plastic)	SOT163-1		
S.COY	7.5	5 N		
		74F(U.L.)	10	AD VALUE

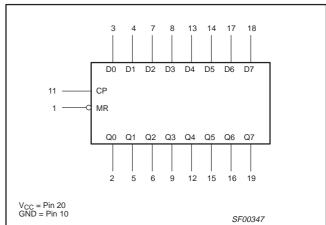
INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

PINS	DESCRIPTION	74F(U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
D0 – D7	Data inputs	1.0/0.033	20μΑ/20μΑ
MR	Master Reset input (active–Low)	1.0/0.033	20μΑ/20μΑ
СР	Clock pulse input (active rising edge)	1.0/0.033	20μΑ/20μΑ
Q0 – Q7	Data outputs	50/33	1.0mA/20mA

PIN CONFIGURATION



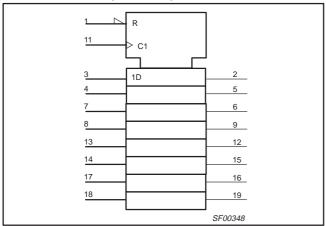
LOGIC SYMBOL



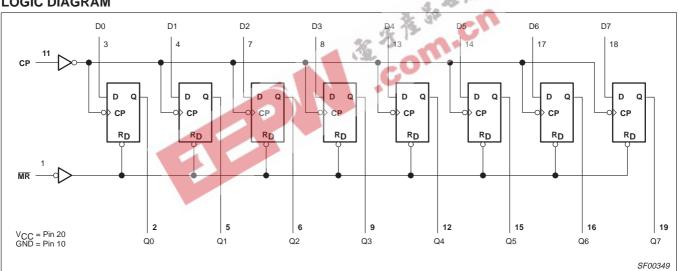
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LOGIC SYMBOL (IEEE/IEC)







FUNCTION TABLE

	INPUTS		OUTPUTS	OPERATING
MR	СР	Dn	Q0 – Q7	MODE
L	Х	Х	L	Reset (clear)
Н	↑	h	Н	Load "1"
Н	↑	I	L	Load "0"

High voltage level

High voltage level one set-up time prior to the Low-to-High clock transition

L

Low voltage level one set—up time prior to the Low—to—High clock transition Don't care
Low—to—High clock transition Ī X ↑

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ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limit set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT
V _{CC}	Supply voltage	-0.5 to +7.0	V
V _{IN}	Input voltage	-0.5 to +7.0	V
I _{IN}	Input current	-30 to +5	mA
V _{OUT}	Voltage applied to output in High output state	–0.5 to V _{CC}	V
I _{OUT}	Current applied to output in Low output state	40	mA
T _{amb}	Operating free air temperature range	0 to +70	°C
T _{stg}	Storage temperature range	-65 to +150	°C

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	A A	UNIT		
	3	MIN	TYP	MAX	
V _{CC}	Supply voltage	4.5	5.0	5.5	V
V _{IH}	High-level input voltage	2.0			V
V _{IL}	Low-level input voltage			0.8	V
I _{Ik}	Input clamp current			-18	mA
I _{OH}	High-level output current			-1	mA
I _{OL}	Low-level output current			20	mA
T _{amb}	Operating free air temperature range	0		+70	°C

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DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	PARAMETER		TEST	LIMITS			UNIT	
			CONDITIONS	MIN	TYP ²	MAX		
		MR & CP	$V_{CC} = MIN, V_{IL} = 0.0V^3,$	±10%V _{CC}	2.5			V
V_{OH}	High-level output voltage	inputs	$V_{IH} = 4.5V^3$, $I_{OH} = MAX$	±5%V _{CC}	2.7	3.4		V
		other	$V_{CC} = MIN, V_{IL} = MAX,$	±10%V _{CC}	2.5			V
		inputs	$V_{IH} = MIN, I_{OH} = MAX$	±5%V _{CC}	2.7	3.4		V
V _{OL}	Low-level output voltage		$V_{CC} = MIN, V_{IL} = MAX,$	±10%V _{CC}		0.30	0.50	V
			$V_{IH} = MIN, I_{OH} = MAX$	±5%V _{CC}		0.30	0.50	V
V_{IK}	Input clamp voltage		$V_{CC} = MIN, I_I = I_{IK}$		-0.73	-1.2	V	
lį	Input current at maximum input	voltage	$V_{CC} = 0.0V, V_I = 7.0V$			100	μΑ	
I _{IH}	High-level input current		$V_{CC} = MAX, V_I = 2.7V$				20	μΑ
I_{IL}	Low-level input current		$V_{CC} = MAX, V_I = 0.5V$			-20	μΑ	
I _{OS}	Short–circuit output current ⁴	V _{CC} = MAX		-60		-150	mA	
I _{CC}	Supply current (total)	I _{CCH}	V _{CC} = MAX	C		24	38	mA
		I _{CCL}	18 3		27	43	mA	

NOTES:

- 1. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
- 2. All typical values are at $V_{CC} = 5V$, $T_{amb} = 25$ °C.
- 3. To reduce the effect of external noise during test
- 4. Not more than one output should be shorted at a time. For testing los, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, los tests should be performed last.

AC CHARACTERISTICS FOR 'F273A

SYMBOL PARAMETER		PARAMETER WAVEFORM		$c_{amb} = +25^{\circ}$ $c_{CC} = +5.0^{\circ}$ $c_{L} = 50$ $c_{L} = 500$	V	T _{amb} = 0°C V _{CC} = +5 C _L = R _L =	UNIT	
			Min	Тур	Max	Min	Max	
f _{MAX}	Maximum clock frequency	1	150	170		125		MHz
t _{PLH} t _{PHL}	Propagation delay CP to Qn	1	3.5 5.0	5.0 7.0	8.0 9.5	3.0 4.5	9.0 10.0	ns
t _{PHL}	Propagation delay MR to Qn	2	5.0	7.0	9.0	5.0	9.5	ns

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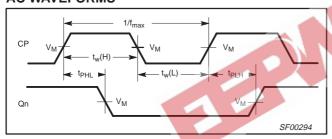
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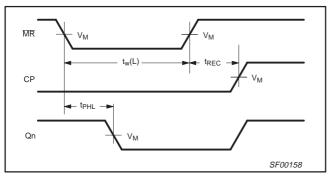
AC SETUP REQUIREMENTS FOR 'F273A

SYMBOL	PARAMETER	WAVEFORM	\ \ \	$c_{amb} = +25^{\circ}$ $c_{CC} = +5.0^{\circ}$ $c_{L} = 50$ $c_{L} = 500$	V :	T _{amb} = 0°C V _{CC} = +5 C _L = R _L =	50pF	UNIT
			Min	Тур	Max	Min	Max	
t _s (H) t _s (L)	Setup time, High or Low Dn to CP	3	3.0 2.0			2.5 2.5		
t _h (H) t _h (L)	Hold time, High or Low Dn to CP	3	0.5 0.0			2.5 1.0		ns
t _w (H) t _w (L)	Clock pulse width High or Low	1	4.5 3.5			5.0 4.0		ns
t _w (L)	Master Reset pulse width, Low	2	3.0			3.5		ns
t _{REC}	Recovery time MR to CP	2	4.0	4.	本是	5.0		ns

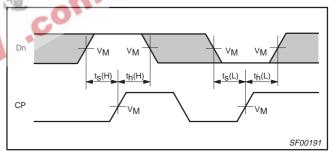
AC WAVEFORMS



Waveform 1. Propagation Delay, Clock Input to Output, Clock Pulse Width, and Maximum Clock Frequency



Waveform 2. Master Reset Pulse Width, Master Reset to Output **Delay and Master Reset to Clock Recovery Time**



Waveform 3. Data Setup and Hold Times

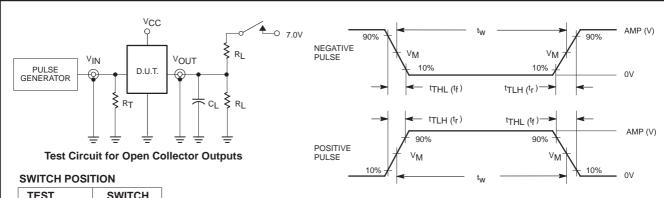
 $\label{eq:NOTE:Por all waveforms, V_M = 1.5V.}$ The shaded areas indicate when the input is permitted to change for predictable output

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TEST CIRCUIT AND WAVEFORMS



TEST	SWITCH
t _{PLZ}	closed
t _{PZL}	closed
All other	open

DEFINITIONS:

R_L = Load resistor;
see AC electrical characteristics for value.

C_L = Load capacitance includes jig and probe capacitance;
see AC electrical characteristics for value.

Termination resistance should be equal to Z_{OUT} of pulse generators.

	30	INP	UT PU	LSE REQU	REMEN	TS	
ď	amily	amplitude	VM	rep. rate	t _w	t _{TLH}	t _{THL}
	7 4F	3.0V	1.5V	1MHz	500ns	2.5ns	2.5ns

Input Pulse Definition

SF00128

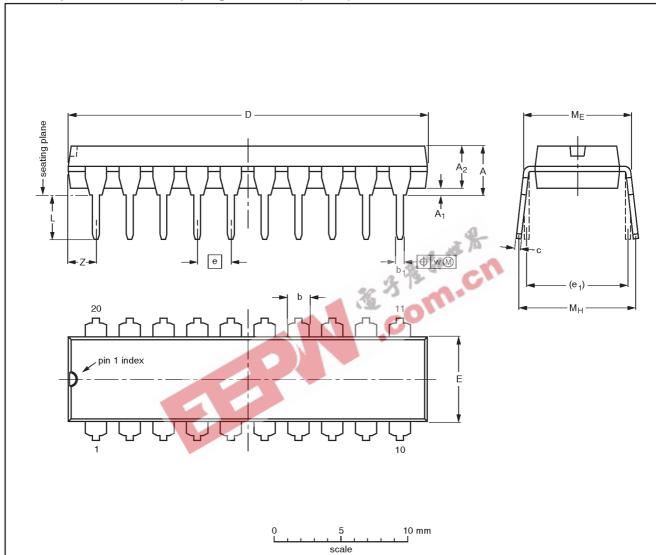


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DIP20: plastic dual in-line package; 20 leads (300 mil)

SOT146-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

	` `			aciii va i				,							
UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	c	D ⁽¹⁾	E ⁽¹⁾	е	e ₁	L	ME	Мн	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	0.36 0.23	26.92 26.54	6.40 6.22	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.0
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.014 0.009	1.060 1.045	0.25 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.078

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT146-1			SC603			-92-11-17 95-05-24

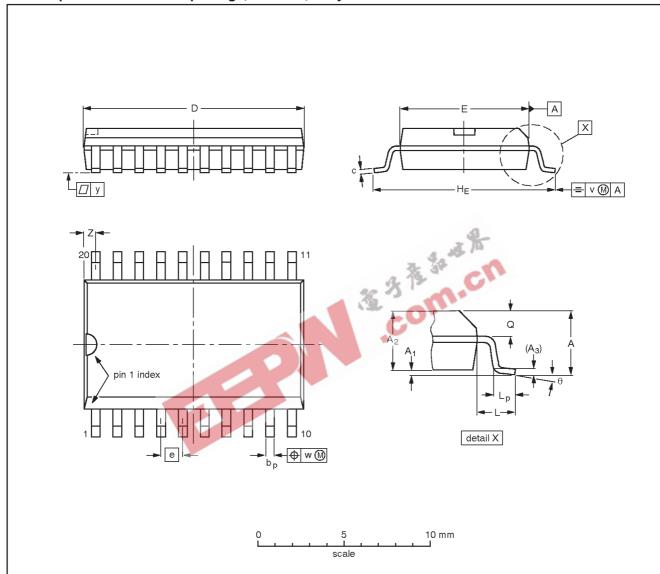
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SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

DIMENTO							****			,								
UNIT	A max.	A ₁	A ₂	А3	bр	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	٧	w	у	z ⁽¹⁾	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.050	0.419 0.394	0.055	0.043 0.016		0.01	0.01	0.004	0.035 0.016	o°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT163-1	075E04	MS-013AC				-95-01-24 97-05-22

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Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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^[1] Please consult the most recently issued datasheet before initiating or completing a design.

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